Silicon Carbide Schottky Diode

650 V, 8 A

Silicon Carbide (SiC) Schottky Diodes use a completely new technology that provides superior switching performance and higher reliability compared to Silicon. No reverse recovery current, temperature independent switching characteristics, and excellent thermal performance sets Silicon Carbide as the next generation of power semiconductor. System benefits include highest efficiency, faster operating frequency, increased power density, reduced EMI, and reduced system size and cost.

Features

- Max Junction Temperature 175°C
- Avalanche Rated 33 mJ
- High Surge Current Capacity
- Positive Temperature Coefficient
- Ease of Paralleling
- No Reverse Recovery / No Forward Recovery
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

Applications

- General Purpose
- SMPS, Solar Inverter, UPS
- Power Switching Circuits

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Parameter	Symbol	Value	Unit	
Peak Repetitive Reverse Voltage	V_{RRM}	650	V	
Single Pulse Avalanche Energy ($I_{L(pk)} = 11.5 \text{ A}, L = 0.5 \text{ mH}, V = 50$	E _{AS}	33	mJ	
Continuous Rectified Forward Current	@ T _C < 147	IF	8.0	Α
Current	@ T _C < 135		10.1	
Non-Repetitive Peak Forward Surge Current	$T_C = 25^{\circ}C$ $t_P = 10 \mu s$	I _{FM}	551	Α
	T _C = 150°C t _P = 10 μs		498	
Non-Repetitive Forward Surge Current (Half-Sine Pulse)	$T_{C} = 25^{\circ}C$ $t_{P} = 8.3 \text{ ms}$	I _{FSM}	56	Α
Power Dissipation	T _C = 25°C	P _{tot}	73	W
	T _C = 150°C		12	
Operating Junction and Storage T Range	T _J , T _{stg}	-55 to +175	°C	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

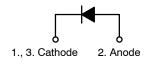
Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case, Max.	$R_{ heta JC}$	2.05	°C/W



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V _{RRM}	l _F
650 V	8.0 A

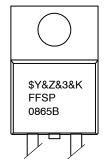


Schottky Diode



TO-220-2LD CASE 340BB

MARKING DIAGRAM



\$Y = ON Semiconductor Logo &Z = Assembly Plant Code &3 = Numeric Date Code &K = Lot Code

FFSP0865B = Specific Device Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
ON CHARACTERISTICS			•			
Forward Voltage	V _F	I _F = 8.0 A, T _J = 25°C		1.39	1.7	V
		I _F = 8.0 A, T _J = 125°C		1.55	2.0	
		I _F = 8.0 A, T _J = 175°C		1.71	2.4	
Reverse Current	I _R	V _R = 650 V, T _J = 25°C		0.073	40	μΑ
		V _R = 650 V, T _J = 125°C		0.24	80	
		V _R = 650 V, T _J = 175°C		0.48	160	
CHARGES, CAPACITANCES & G	SATE RESISTANCE					
Total Capacitive Charge	Q _C	V _C = 400 V		22		nC
	C _{tot}	V _R = 1 V, f = 100 kHz		336		pF
		V _R = 200 V, f = 100 kHz		39		
		V _R = 400 V, f = 100 kHz		30		

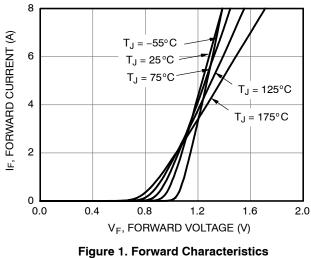
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Marking	Package	Packing Method	Reel Size	Tape Width	Quantity
FFSP0865B	FFSP0865B	TO220	Tube	N/A	N/A	50 Units

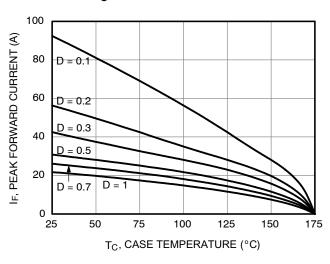
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

TYPICAL CHARACTERISTICS



10⁻⁶ IR, REVERSE CURRENT (A) 10 -7 TJ= 175°0 T_J = 125°C 10- $T_{J} = 75^{\circ}C$ $T_{J} = 25^{\circ}C$ 10 100 300 500 200 400 600 650 V_R, REVERSE VOLTAGE (V)

Figure 2. Reverse Characteristics



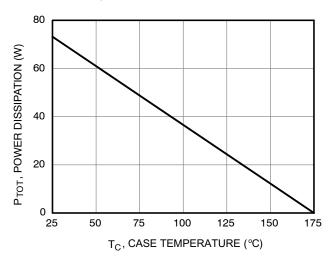
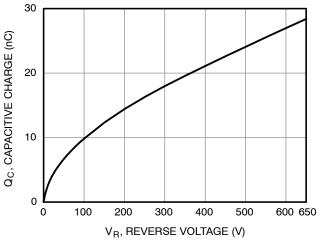


Figure 3. Current Derating

Figure 4. Power Derating



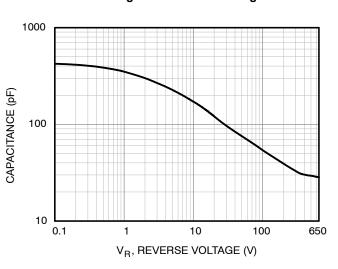


Figure 5. Capacitive Charge vs. Reverse Voltage

Figure 6. Capacitance vs. Reverse Voltage

TYPICAL CHARACTERISTICS

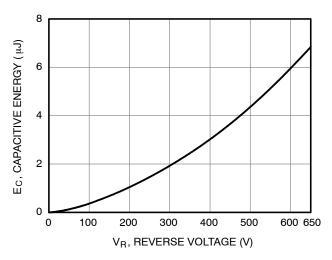


Figure 7. Capacitance Stored Energy

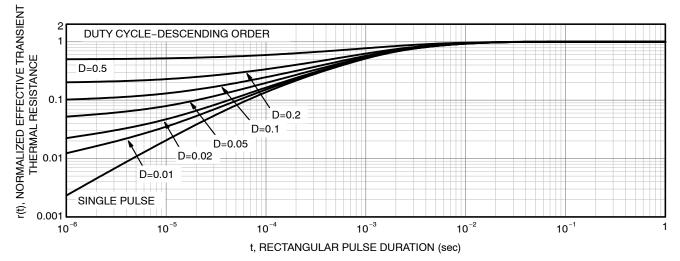
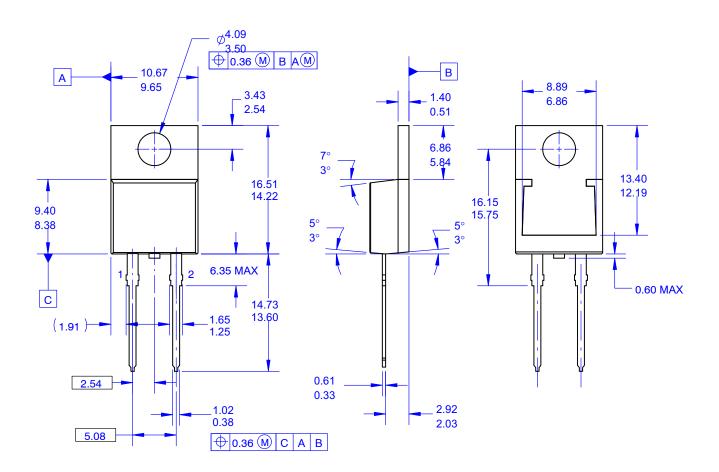


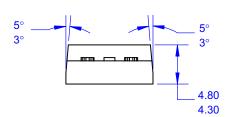
Figure 8. Junction-to-Case Transient Thermal Response



TO-220-2LD CASE 340BB ISSUE O

DATE 31 AUG 2016





NOTES:

- A. PACKAGE REFERENCE: JEDEC TO220,ISSUE K, VARIATION AC,DATED APRIL 2002.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSION AND TOLERANCE AS PER ASME Y14.5-2009.
- D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.

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DESCRIPTION:	TO-220-2LD		PAGE 1 OF 1	

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